

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bruce J. Freyman, et al.
 Assignee: Amkor Electronics, Inc.
 Title: MOLD RUNNER REMOVAL FROM A SUBSTRATE BASED
 PACKAGED ELECTRONIC DEVICE

Serial No.: 08/214,339 Filed: March 16, 1994

Examiner: Decker, R. Group Art Unit: 2104

Attorney Docket No.: M-2556 US

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GROUP 2100

San Jose, California
 July 12, 1996

COMMISSIONER OF PATENTS AND TRADEMARKS
 Washington, D. C. 20231

RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action mailed April 18, 1996,
 please amend the above-identified application as follows.

IN THE CLAIMS

Please cancel Claims 15-22.

Please amend Claims 1-14 as follows:

1. (AMENDED) A substrate-based packaged electronic
 device, comprising:

a substrate having first and second surfaces[,
 wherein:]

a degating region [is formed] on the first surface of
 the substrate;

a degating region material on the degating region;
 [and]

a structure for making external electrical connection
from the substrate-based packaged electronic device [is
formed] on the second surface of the substrate;

an electronic device attached to the first surface of
 the substrate, the electronic device being electrically
 connected to the structure for making external electrical
 connection; and

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